

**LPT16ED****30 GHz SiGe Bipolar Transistor
Final**

Applications

- Low phase noise oscillators up to 16 GHz
- VCO's, DRO's and YIG oscillators
- Point-to-point radios
- Satellite communications
- Fiber optics, OC-192 and OC-768
- Local Multipoint Distribution Systems, LMDS

Features

- Low 1/f noise: -142 dBc/Hz at 100 Hz offset
- Phase noise: -167 dBc/Hz at 100 kHz offset
- Output power up to +13 dBm
- Operation down to 1 volt, 2 mA
- Gold bump pads for wire bond or flip chip (for direct die attachment)

Product Description

The LPT16ED is a silicon germanium low phase noise, high frequency NPN transistor for oscillator applications up to 16GHz.

The transistor exhibits low 1/f noise and provides +13 dBm typical output power at V_{CE} of 3V and I_C equal to 20 mA. It is easily operated from a single supply voltage with appropriate external passive components.

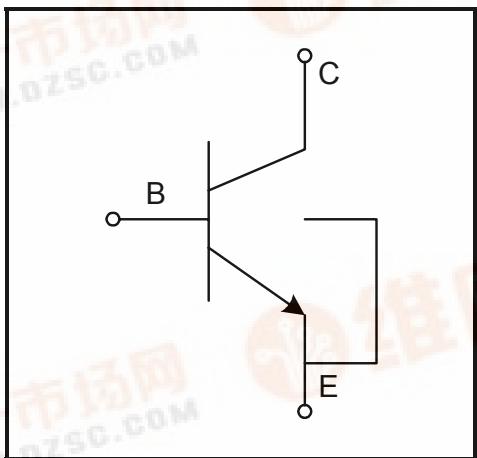
The silicon germanium technology used in this device provides outstanding high-frequency performance combined with high thermal conductivity and superior reliability under harsh operating and storage conditions.

A complete mechanical description of the transistor is available under SiGe Semiconductor Document 07MS001.

Ordering Information

| Type | Package | Remark |
|---------|----------|------------------------|
| LPT16ED | Bare Die | Shipped in Waffle Pack |

Functional Block Diagram



Absolute Maximum Ratings

Operation in excess of any one of Absolute Maximum Ratings may result in permanent damage. This is a high performance RF device with ESD rating < 2keV. Handling and assembly of this device should be done at ESD protected workstations.

| Symbol | Parameter | Min. | Max. | Unit |
|-----------|------------------------------|------|-------|------|
| V_{CBO} | Collector to Base Voltage | | +13.0 | V |
| V_{CEO} | Collector to Emitter Voltage | | +4.0 | V |
| V_{EBO} | Emitter to Base Voltage | | +1.5 | V |
| I_C | Collector Current | | 80 | mA |
| I_B | Base Current | | 2.0 | mA |
| P_T | Total Power Dissipation | | 250 | mW |
| T_j | Junction Temperature | | +150 | °C |
| T_{STG} | Storage Temperature | -65 | +150 | °C |

DC Electrical Characteristics

Conditions: T_A = unless otherwise specified 25°C

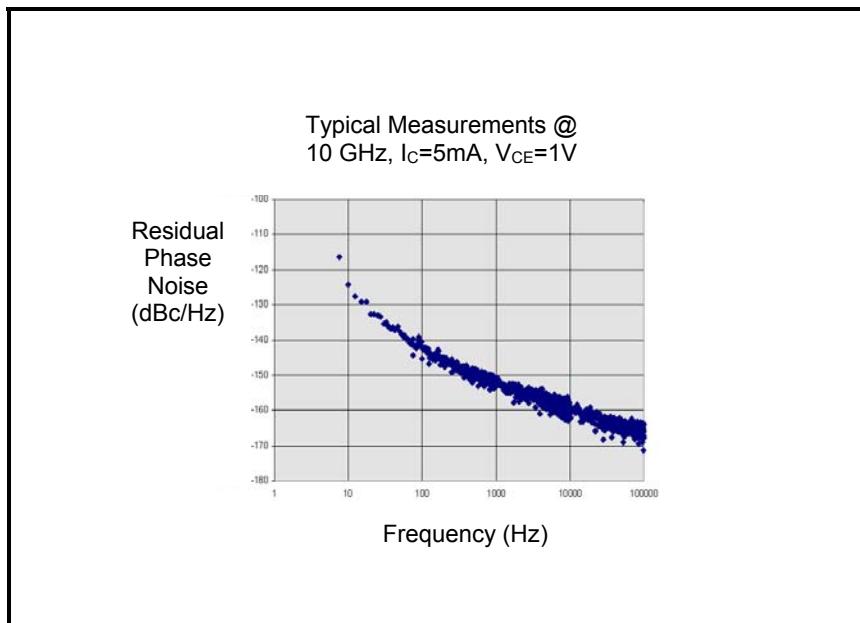
| Symbol | Parameter | Condition | Min. | Typ. | Max. | Unit |
|------------|-------------------------------------|-----------------------------------|------|------|------|------|
| V_{BE} | Base-emitter voltage | $I_C = 1\mu A$ | 670 | 687 | 700 | mV |
| BV_{CEO} | Collector-emitter breakdown voltage | Open base | 4.0 | 4.5 | 5.0 | V |
| BV_{CES} | Collector-emitter breakdown voltage | Base-emitter shorted via 100kΩ | 14 | 15.0 | 16 | V |
| BV_{EBO} | Emitter-base breakdown voltage | $I_E = 100\mu A$, open collector | 2.0 | 2.3 | 2.6 | V |
| BV_{CBO} | Collector-base breakdown voltage | Open emitter | 14 | 15.0 | 16 | V |
| V_A | Early voltage | $I_C = 10mA$, $V_{CE} = 3V$ | 100 | 200 | 300 | V |
| I_{CBO} | Collector-base cutoff current | $V_{CB} = 5V$ and $I_E = 0$ | | | 100 | pA |
| I_{EBO} | Emitter-base cutoff current | $V_{EB} = 1.5V$ and $I_C = 0$ | 5 | 10 | 15 | μA |
| h_{FE} | DC current gain | $V_{CE} = 2V$, $I_C = 20mA$ | 50 | 60 | 150 | |

AC Electrical Characteristics

| Symbol | Parameter | Note | Min. | Typ. | Max. | Unit |
|---------------------------------|---|---|------|------|------|------|
| IS ₂₁ I ₂ | Insertion Power Gain (Z _S = Z _L = 50Ω) | V _{CE} = 1.5V, I _C = 10mA, f = 16GHz | 0.7 | 1.0 | 1.3 | dB |
| | | V _{CE} = 3.0V, I _C = 20mA, f = 16GHz | 2.3 | 2.6 | 2.9 | dB |
| MAG/ MSG | Maximum Available Gain or Maximum Stable Gain | V _{CE} = 1.5V, I _C = 10mA, f = 16GHz | 3.3 | 3.6 | 4.2 | dB |
| | | V _{CE} = 3.0V, I _C = 20mA, f = 16GHz | 4.9 | 5.2 | 5.6 | dB |

Typical Performance Characteristics

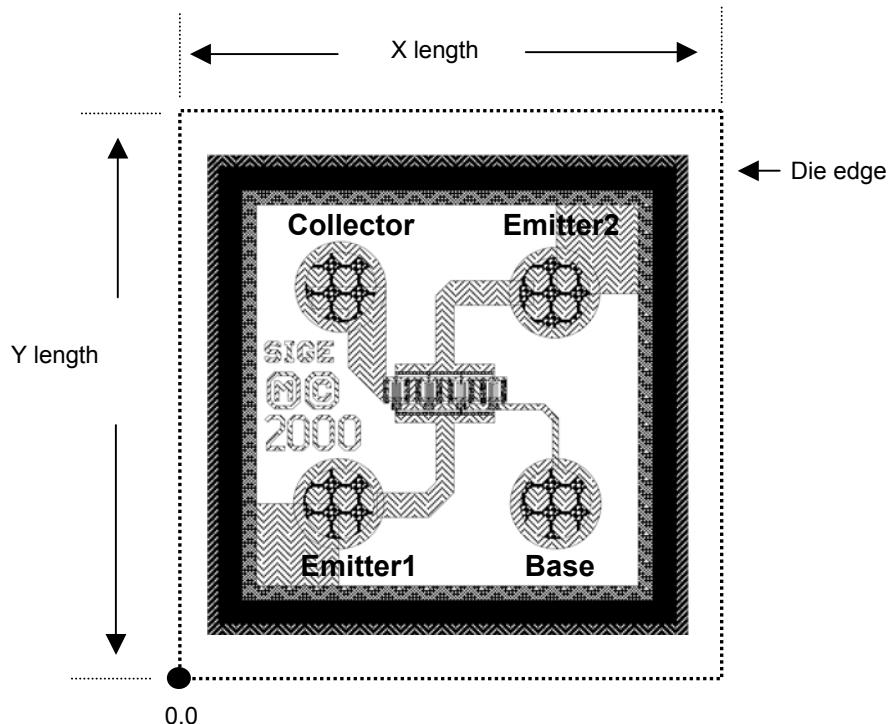
Please refer to application note (Document 07AN001).



Typical Applications Information

Series or parallel feedback oscillators at 5-16 GHz. (Please refer to application note, Document 07AN001).

Die and Pad Description



Dimensions are relative to the 0,0 cut die corner.

| Feature | Specification | Comments |
|-----------------------|--------------------|--------------------------|
| Die thickness | 10 mil +/- 1mil | |
| X length | 15.3 mil +/- 1mil | |
| Y length | 14.5 mil +/- 1mil | |
| Pad diameter | 2.9 mil +/- 0.1mil | Pads are circular. |
| Pad pitch | 6 mil +/- 0.1mil | Pad center to pad centre |
| Pad/bump height | 1 mil +/- 0.05mil | |
| Pad/bump co-planarity | 0.2 mil | |

| Pad Center | Position (X mil, Y mil) +/- 0.7mil relative to the 0,0 cut die corner |
|------------|---|
| Collector | 5, 11 |
| Emitter1 | 5, 5 |
| Base | 11, 5 |
| Emitter 2 | 11, 11 |

Please refer to Document 01-MS-001 for SiGe's die inspection criteria.

For S-parameter data, please refer to SiGe Document 07SP001.

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Product Preview

The datasheet contains information from the product concept specification. SiGe Semiconductor Inc. reserves the right to change information at any time without notification.

Preliminary Information

The datasheet contains information from the design target specification. SiGe Semiconductor Inc. reserves the right to change information at any time without notification.

Final

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